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DOCKET NO.: 2336-034 To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto: 2. Name and address of receiving party(ies) 1. Name of conveying party(ies): Name: SAMSUNG ELECTRO-MECHANICS CO., LTD. Keon Yang PARK Byung Kook SUN Jae Heun JOUNG Dong SHIN Internal Address: Additional name(s) of conveying party(ies) attached? Yes X No 3. Nature of conveyance: X Assignment Street Address: 314 Maetan-dong, Paldal-ka, Suwon-si, Kyungki-_ Merger Republic of Korea __ Change of Name Security Agreement State/Country: ZIP: ___ Other __ Execution Date: November 23, 1998 Additional name(s) & address(es) attached? Yes 4. Application number(s) or patent number(s): If the document is being filed together with a new application, the execution date of the application is: November 23, 1998 B. Patent No(s). Patent Application No(s). Additional numbers attached? \underline{X} Yes \underline{X} No 6. Total number of applications and patents involved: 1 5. Name and address of party to whom correspondence concerning document should be mailed: 12/10/1998 GUASHING 00000054 09203489
Name LOWE HAUPTMAN GOPSTEIN GILMAN & BERNER 7. Total fee (37 CFR 3.41)..... \$40.00 40.00 DP 04 FC:581 X Enclosed Internal Address: _ Authorized to be charged to deposit account Street Address: 2034 Eisenhower Avenue, Suite 200 8. Deposit account number: 07-1337 ZIP:22314 City:Alexandria State: VA DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document December 2, 1998 Benjamin J. Hauptman, Reg. No. 29,310 Name and Registration No. of Person Signing Date Total number of pages comprising cover sheet: 1 CMB No. 0851-0011 (exp. 4/94)

> **PATENT** REEL: 9651 FRAME: 0917

(2) Byung Kook Sun

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(5)

(1) Keon Yang Park (4) Dong Shin

(3) Jae Heun Joung (6)
who has made a certain new and useful invention, hereby sell, assign and transfer unto
SAMSUNG ELECTRO-MECHANICS CO., LTD
314 Maetan-dong, Paldal-ku, Suwon-si
Kyungki-do, Republic of Korea
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled <u>METHOD FOR MANUFACTURING MULTI-LAYER PRINTED CIRCUIT BOARD</u>
(a) for which an application for United States Letters Patent was filed on, and identified by United States Serial No; or
(b) for which an application for United States Letters Patent was executed on,
and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United

legal representatives; the undersigned agree that the attorneys of record in

said application shall hereafter act on behalf of said ASSIGNEE;

PATENT REEL: 9651 FRAME: 0918 States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

RECORDED: 12/02/1998

INVENTOR(S)	DATE SIGNED
1) Kennyang Rak Name: Keon Yang PARK	Nov. 23. 1988
2) Bywekok Com Name: Byung Kook SUN	Nov 23, 1998
3) <u>far ham Jinang</u> Name: Jae Heun JOUNG	Nov. 23, 1995
4) Dong Shin	Nev. 23, 1998

PATENT REEL: 9651 FRAME: 0919